

## HVM187WK

### Silicon Epitaxial Planar Pin Diode for High Frequency Attenuator

REJ03G0116-0600Z  
(Previous: ADE-208-056E)  
Rev.6.00  
Oct.08.2003

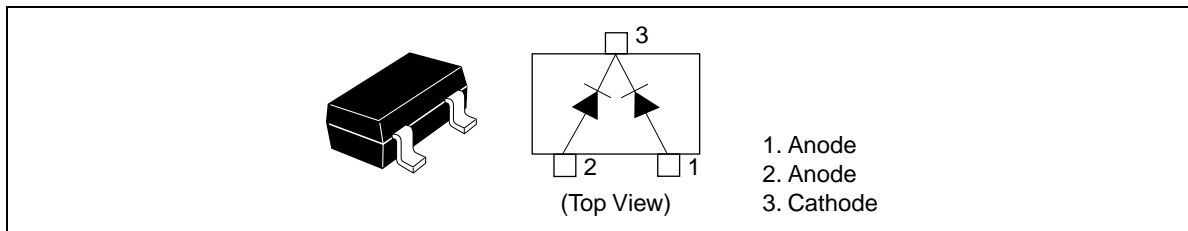
#### Features

- Low forward resistance. ( $r_f = 5.5 \Omega$  max)
- MPAK package is suitable for high density surface mounting and high speed assembly.

#### Ordering Information

Type No.	Laser Mark	Package Code
HVM187WK	H1	MPAK

#### Pin Arrangement



**Absolute Maximum Ratings**

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	60	V
Forward current	I <sub>F</sub>	50	mA
Power dissipation	Pd * <sup>1</sup>	100	mW
Junction temperature	T <sub>J</sub>	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C

Note: 1. Per one device.

**Electrical Characteristics \*<sup>1</sup>**

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I <sub>R</sub>	—	—	100	nA	V <sub>R</sub> = 60 V
Forward voltage	V <sub>F</sub>	—	—	1.0	V	I <sub>F</sub> = 10 mA
Capacitance	C	—	—	2.4	pF	V <sub>R</sub> = 0 V, f = 1 MHz
Forward resistance	r <sub>f</sub>	3.5	—	5.5	Ω	I <sub>F</sub> = 10 mA, f = 100 MHz
ESD-Capability * <sup>2</sup>	—	200	—	—	V	C = 200 pF, Both forward and reverse direction 1 pulse.

Notes: 1. Per one device.

2. Failure criterion ; I<sub>R</sub> ≥ 100 nA at V<sub>R</sub> = 60 V

Main Characteristic

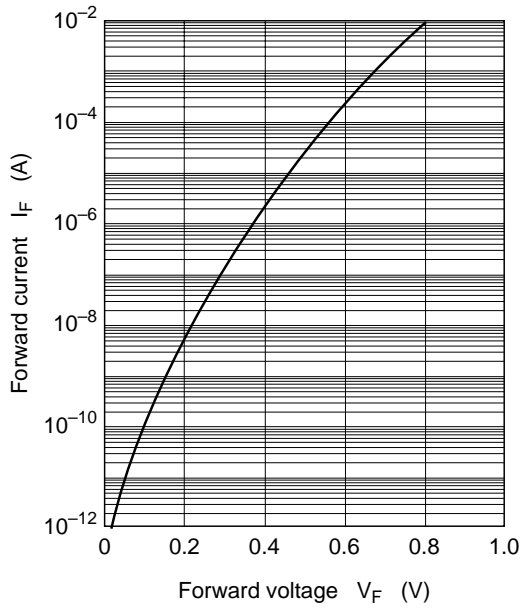


Fig.1 Forward current vs. Forward voltage

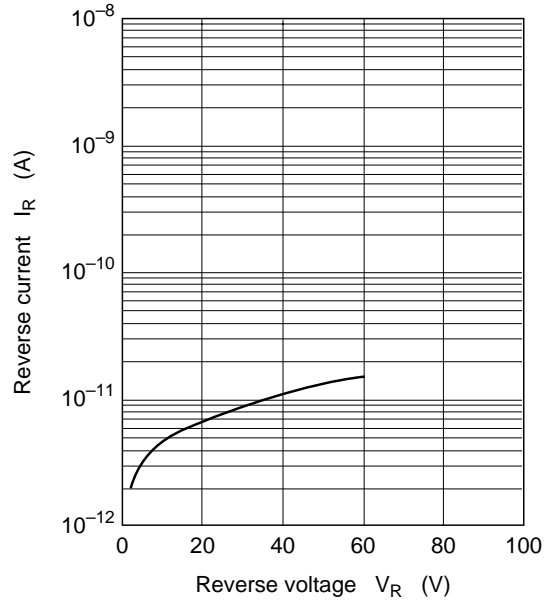


Fig.2 Reverse current vs. Reverse voltage

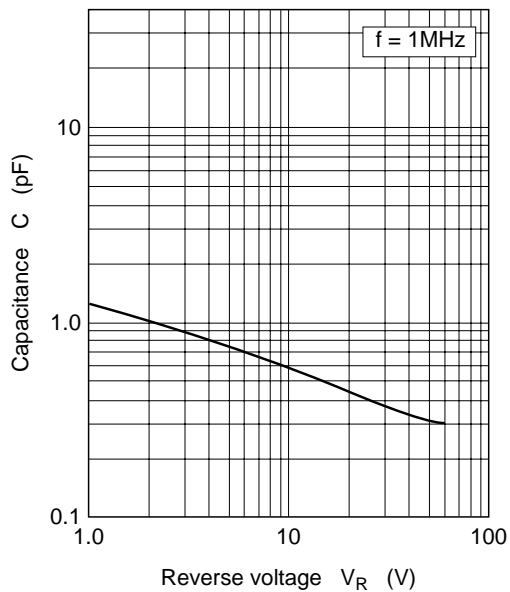


Fig.3 Capacitance vs. Reverse voltage

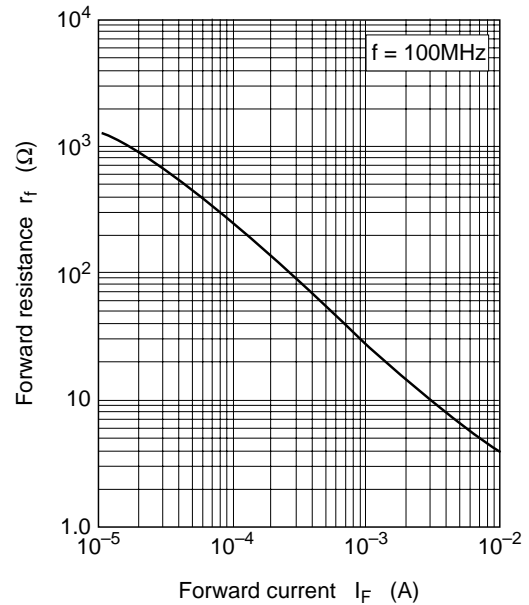
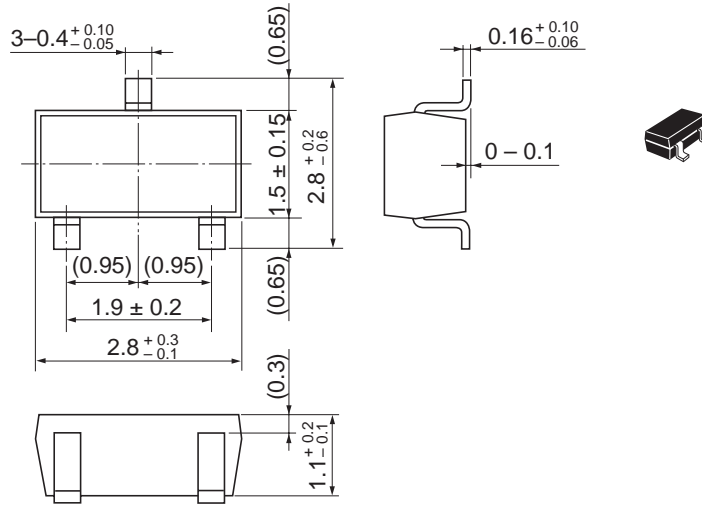


Fig.4 Forward resistance vs. Forward current

Package Dimensions

As of January, 2003  
Unit: mm



Package Code	MPAK
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.011 g

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